

8A, 100V - 200V Ultra Fast Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Planar technology
- Low power loss, high efficiency
- Ideal for automated placement
- Wettable flank
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

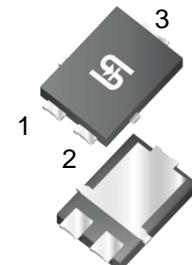
KEY PARAMETERS		
PARAMETER	VALUE	UNIT
I_F	8	A
V_{RRM}	100 - 200	V
I_{FSM}	200	A
$T_J \text{ MAX}$	175	°C
Package	TO-277A (SMPC4.6U)	
Configuration	Single die	

APPLICATIONS

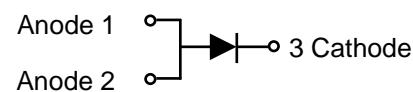
- High frequency switching
- DC/DC
- Snubber

MECHANICAL DATA

- Case: TO-277A (SMPC4.6U)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.104g (approximately)



TO-277A (SMPC4.6U)



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)				
PARAMETER	SYMBOL	PUUP8BH	PUUP8DH	UNIT
Marking code on the device		PU8BH	PU8DH	
Repetitive peak reverse voltage	V_{RRM}	100	200	V
Reverse voltage, total rms value	$V_{R(\text{RMS})}$	70	140	V
Forward current	I_F	8		A
Surge peak forward current single half sine-wave superimposed on rated load	$t = 8.3\text{ms}$	I_{FSM}	200	A
	$t = 1.0\text{ms}$		410	
Junction temperature	T_J	-55 to +175		°C
Storage temperature	T_{STG}	-55 to +175		°C

THERMAL PERFORMANCE

PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance ⁽¹⁾	$R_{\Theta JL}$	2.0	°C/W
Junction-to-ambient thermal resistance ⁽²⁾	$R_{\Theta JA}$	48.7	°C/W
Junction-to-case thermal resistance ⁽²⁾	$R_{\Theta JC}$	9.0	°C/W

Thermal Performance Notes:

1. With ideal heat sink
2. Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	$I_F = 4\text{A}, T_J = 25^\circ\text{C}$	V_F	0.81	-	V
	$I_F = 8\text{A}, T_J = 25^\circ\text{C}$		0.88	1.05	V
	$I_F = 4\text{A}, T_J = 125^\circ\text{C}$		0.67	-	V
	$I_F = 8\text{A}, T_J = 125^\circ\text{C}$		0.75	-	V
Reverse current @ rated V_R ⁽²⁾	$T_J = 25^\circ\text{C}$	I_R	-	2	μA
	$T_J = 125^\circ\text{C}$		-	15	μA
Junction capacitance	1MHz, $V_R = 4.0\text{V}$	C_J	96	-	pF
Reverse recovery time	$I_F = 0.5\text{A}, I_R = 1.0\text{A}, I_{rr} = 0.25\text{A}$	t_{rr}	-	25	ns
	$I_F = 1.0\text{A}, dI/dt = 50\text{A}/\mu\text{s}, V_R = 30\text{V}$		31	-	
Reverse recovery current	$I_F = 8.0\text{A}, dI/dt = 200\text{A}/\mu\text{s}, V_R = 100\text{V}$	I_{RM}	5.6	-	A
Reverse recovery charge		Q_{rr}	89	-	nC
Reverse recovery time		t_{rr}	31	-	ns

Notes:

1. Pulse test with PW = 0.3ms
2. Pulse test with PW = 30ms

ORDERING INFORMATION

ORDERING CODE ⁽¹⁾	PACKAGE	PACKING
PUUP8xH	TO-277A (SMPC4.6U)	6,000/ Tape & Reel

Notes:

1. "x" defines voltage from 100V(PUUP8BH) to 200V(PUUP8DH)

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

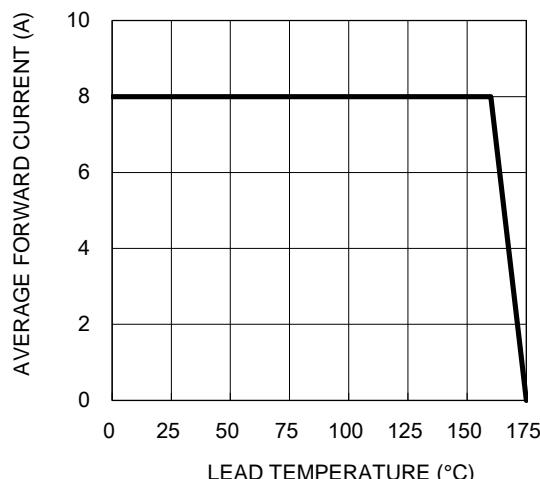


Fig.2 Typical Junction Capacitance

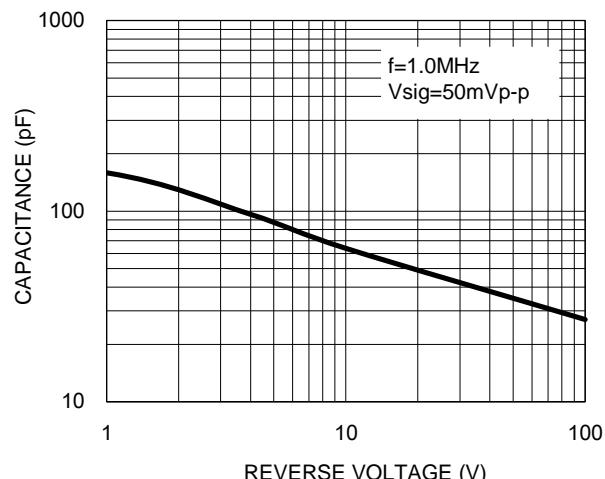


Fig.3 Typical Reverse Characteristics

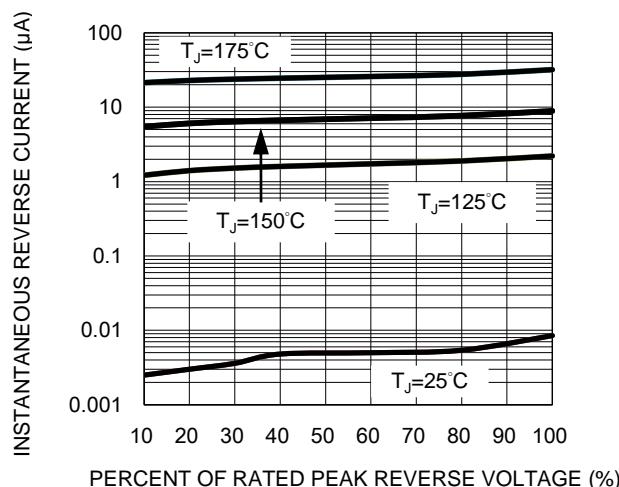


Fig.4 Typical Forward Characteristics

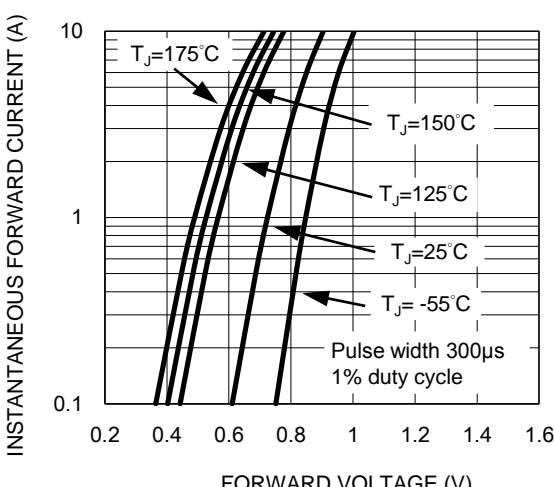
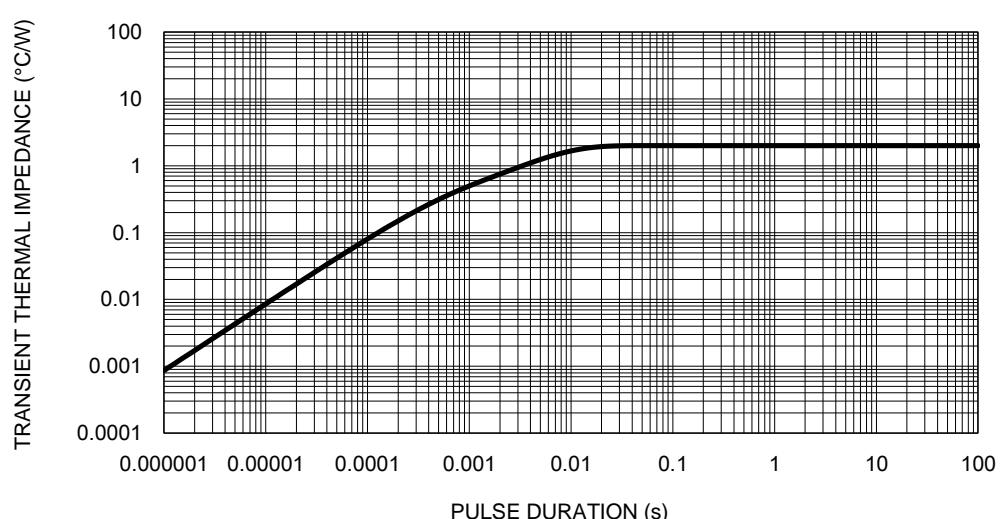
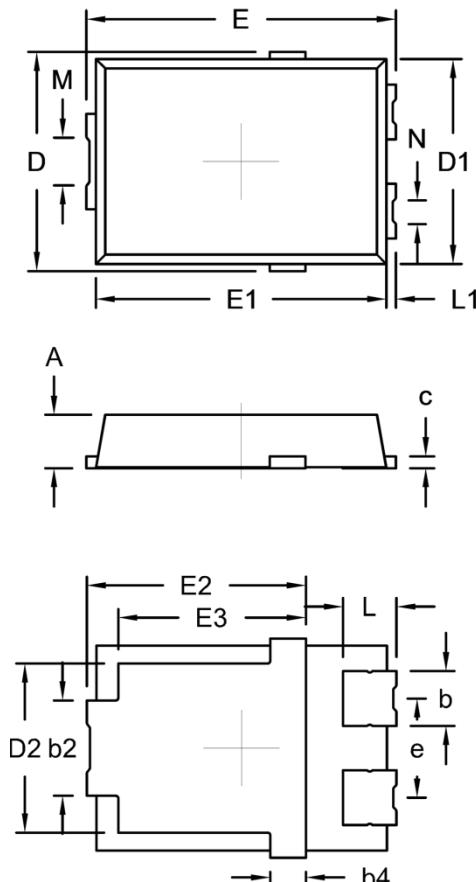


Fig.5 Typical Transient Thermal Impedance



PACKAGE OUTLINE DIMENSIONS

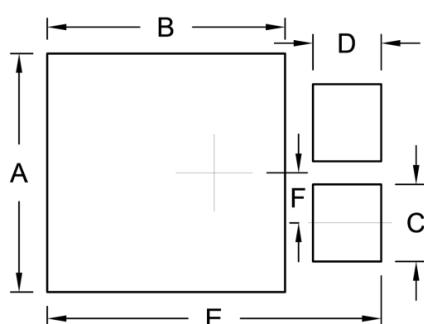
TO-277A (SMPC4.6U)



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	1.00	1.20	0.039	0.047
b	1.05	1.35	0.041	0.053
b2	1.90	2.20	0.075	0.087
b4	0.75 (NOM.)		0.030 (NOM.)	
c	0.15	0.40	0.006	0.016
D	4.45	4.75	0.175	0.187
D1	4.25	4.35	0.167	0.171
D2	3.40	3.70	0.134	0.146
E	6.35	6.65	0.250	0.262
E1	6.05	6.15	0.238	0.242
E2	4.40	4.80	0.173	0.189
E3	3.94 (NOM.)		0.155 (NOM.)	
e	2.08 (NOM.)		0.082 (NOM.)	
L	0.94	1.24	0.037	0.049
L1	0.05	0.35	0.002	0.014
M	0.65	1.15	0.026	0.045
N	0.25	0.75	0.010	0.030

Package body size D1 and E1 do not include mold flash
Mold flash shall not exceed 0.1mm per side

SUGGESTED PAD LAYOUT

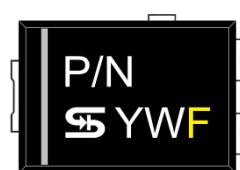


Symbol	Unit (mm)	Unit (inch)
A	4.95	0.195
B	4.95	0.195
C	1.60	0.063
D	1.42	0.056
E	6.95	0.274
F	1.04	0.041

Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

MARKING DIAGRAM



P/N = Marking Code
YW = Date Code
F = Factory Code

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